

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IGB15N60T	**Issued**	08. April 2022
MA#	MA005710470		
Package	PG-TO263-3-2	**Weight***	1557.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.597	0.10	0.10	1026	1026
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.52	19.55	195231	195485
wire	non noble metal	aluminium	7429-90-5	1.650	0.11	0.11	1060	1060
encapsulation	inorganic material	zincoxide	1314-13-2	6.896	0.44		4428	
	miscellaneous	miscellaneous	-	27.583	1.77		17713	
	plastics	epoxy resin	-	103.436	6.64		66422	
	inorganic material	silicondioxide	60676-86-0	551.660	35.43	44.28	354248	442811
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6201	6201
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.035			23	
	noble metal	silver	7440-22-4	0.044			28	
	non noble metal	lead	7439-92-1	1.673	0.11	0.11	1074	1125
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.17	35.22	351686	352144
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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